COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stat d b low next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

CHIP PACKAGE STRUCTURE

the specification of wh	nich					
I hereby state	erial Nothat I have reviewed	and was amended of and understood the coned by any amendment refe	tents of the a	above-identified		
I acknowledge tapplication in accorda I hereby claim for application(s) for pate	he duty to disclose inforce with Title 37, Code oreign priority benefits ent or inventor's certification patent or inventor's centimed:	formation which is material of Federal Regulations, § under Title 35, United Staticate listed below and hartificate having a filing date	al to the paten 1.56(a). es Code, §119 ve also identi	tability of this of any foreign		
Number	Country	Date Filed(yyyy/mm/dd)	Yes	No		
91214106	Taiwan, R.O.C.	2002/9/9	X			
I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application a transact all business in the Patent and Trademark Office connected therewith: Jiawei Huang (Reg. No. 43,330) Charles C.H. Wu (Reg. No. 39,081) Maria Erlinda C. Sarno (Reg. No. 37,436) Belinda Lee (Reg. No. 46,863)						
SEND CORRESPO	NDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)			
J.C. Patents, Inc. 4 Venture, Suite 250, Irvine, CA 92618 (949) 660-0761			Jiawei Huang (949) 660-0762			

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

	Signature:	[h:-)	Hsing	HSM	Date:	June	20	, 2	ومه
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